



**PROJECT INITIATION  
NOTIFICATION SYSTEM FORM**

Project Registration Date (dd-mmm-yyyy) completed by EIA:	1/18/06
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**Electronic Industries Alliance PINS: (01OCT2004)**

1. Project Number Assigned by EIA:	PN-5129		
2. Final Published Document Number Assigned:	EIA-763-A		
3. Title of Final Published Document:	Bare Die and Chip Scale Packages Taped in 8mm & 12mm Carrier Tape for Automatic Handling		
4. Project Intent: (Check the applicable box(s) below)			
Create a New Document		Modify Existing Document	
EIA Component Bulletin	<input type="checkbox"/>	Revise current published document	<input checked="" type="checkbox"/>
EIA standard	<input checked="" type="checkbox"/>	Revise and Redesignate current published document	<input type="checkbox"/>
Joint Industry Document	<input type="checkbox"/>	Revise, Redesignate and Consolidate current document	<input type="checkbox"/>
Create new American National Standard (ANSI)	<input type="checkbox"/>	Revise and Partition current document	<input type="checkbox"/>
Conduct Survey	<input type="checkbox"/>	Reaffirm current document	<input type="checkbox"/>
Other (Please explain↓)	<input type="checkbox"/>	Reaffirm and Redesignate current document	<input type="checkbox"/>
		Supplement to a current document	<input type="checkbox"/>
		Withdraw current document	<input type="checkbox"/>
5. Estimated Project Completion Date (mmm yy):↓		Convert to Historical Document designation	<input type="checkbox"/>
		Other (Please explain↓)	<input type="checkbox"/>
6. Description of Contents of Document: (Provide a one paragraph description, not to exceed 500 characters.)			
Covers requirements for punched and embossed carrier taping of components such as silicon dies, bumped flip devices and chip scale packages			
7. Units of Measurement Used: (check applicable boxes→)	<input checked="" type="checkbox"/> Metric	<input checked="" type="checkbox"/> US	<input type="checkbox"/> Non-Measurement Sensitive
8. Formulating Body (Organization, Committee/Subcommittee Title and Acronym):	Automatic Component Handling Committee (ACH)		
9. Designated Formulating Group Project Author/Editor/Leader: (Specify name and complete contact information, address, phone, email, etc. If none is indicated, Default Project Point Contact will be Formulating Group Chair as completed in 9. below.)			
Name:		Phone:	
Organization:		Fax:	
Address:		Email:	
City, ST, Zip:			
10. Formulating Group Chair: (Specify name and complete contact information, address, phone, email, etc.)			
Name:	Scott Carter	Phone:	630-406-0560
Organization:	Tek Pak, Inc.	Fax:	
Address:	1336 Paramount Parkway	Email:	carter@tekpak.com
City, ST, Zip:	Batavia, IL 60510		

